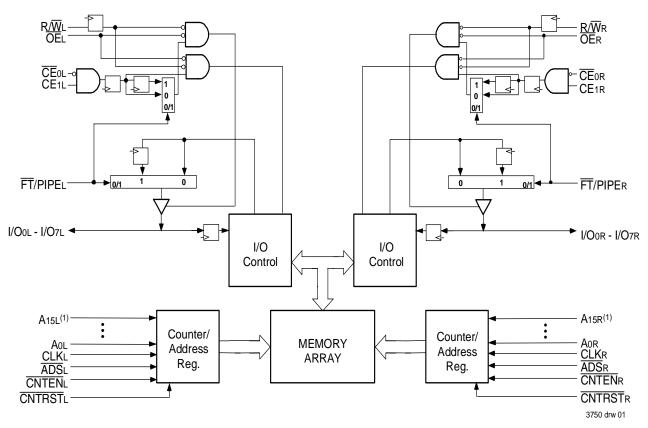


Functional Block Diagram



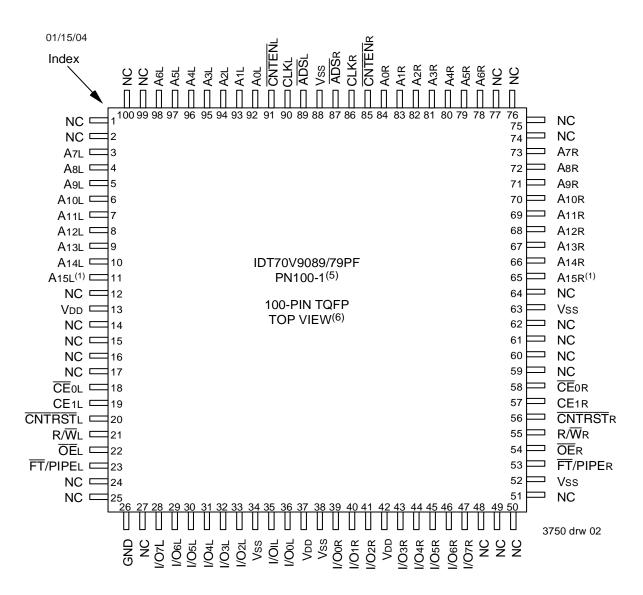
NOTE:

1. A15x is a NC for ID70V9079.

Description:

The IDT70V9089/79 is a high-speed 64/32K x 8 bit synNchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times. With an input data register, the IDT70V9089/79 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by \overline{CE}_0 and CE_1 , permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using IDT's CMOS high-performance technology, these devices typically operate on only 429mW of power.

Pin Configurations^(2,3,4)



- 1. A15x is a NC for ID70V9079.
- 2. All Vcc pins must be connected to power supply.
- 3. All GND pins must be connected to ground.
- 4. Package body is approximately 14mm x 14mm x 1.4mm.
- 5. This package code is used to reference the package diagram.
- 6. This text does not indicate orientation of the actual part-marking.

Pin Names

Left Port	Right Port	Names
CEOL, CE1L	\overline{CE} OR, CE1R	Chip Enables
R/WL	R∕₩r	Read/Write Enable
ŌĒL	<u>OE</u> R	Output Enable
A0L - A15L ⁽¹⁾	A0R - A15R ⁽¹⁾	Address
I/O0L - I/O7L	1/00r - 1/07r	Data Input/Output
CLKL	CLKR	Clock
ADSL	ADSR	Address Strobe
	CNTEN R	Counter Enable
CNTRSTL	CNTRSTR	Counter Reset
FT/PIPEL	FT/PIPER	Flow-Through/Pipeline
VDD		Power (3.3V)
V	SS	Ground (0V)

3750 tbl 01

Truth Table I—Read/Write and Enable Control^(1,2,3)

ŌĒ	CLK	Ē€₀	CE1	R/₩	I/O0-7	Mode
Х	\uparrow	Н	Х	Х	High-Z	Deselected - Power Down
Х	\uparrow	Х	L	Х	High-Z	Deselected - Power Down
Х	\uparrow	L	Н	L	DATAIN	Write
L	\uparrow	L	Н	Н	DATAOUT	Read
Н	Х	L	Н	Х	High-Z	Outputs Disabled
						3750 tbl 02

NOTES:

1. "H" = VIH, "L" = VIL, "X" = Don't Care.

2. \overline{ADS} , \overline{CNTEN} , $\overline{CNTRST} = X$.

3. OE is an asynchronous input signal.

Truth Table II—Address Counter Control^(1,2,3)

External Address	Previous Internal Address	Internal Address Used	CLK	ADS	CNTEN	CNTRST	I/O ⁽³⁾	MODE
An	Х	An	\uparrow	L ⁽⁴⁾	Х	Н	Divo (n)	External Address Used
Х	An	An + 1	1	Н	L ⁽⁵⁾	Н	D⊮o(n+1)	Counter Enabled—Internal Address generation
Х	An + 1	An + 1	1	Н	Н	Н	D⊮o(n+1)	Extemal Address Blocked—Counter disabled (An + 1 reused)
Х	Х	A0	1	Х	х	L ⁽⁴⁾	Di/o(0)	Counter Reset to Address 0
								3750 tbl 03

NOTES:

1. <u>"H"</u> = VIH, <u>"L"</u> = VIL, "X" = Don't <u>Care</u>.

2. \overline{CE}_0 and \overline{OE} = VIL; CE1 and R/ \overline{W} = VIH.

3. Outputs configured in Flow-Through Output mode: if outputs are in Pipelined mode the data out will be delayed by one cycle.

4. ADS and CNTRST are independent of all other signals including CE0 and CE1.

5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CE0 and CE1.

NOTE:

- 1. A15x is a NC for ID70V9079.
- 2. $\overline{\text{LB}}$ and $\overline{\text{UB}}$ are single buffered regardless of state of $\overline{\text{FT}}/\text{PIPE}.$
- CEo and CE1 are single buffered when FT/PIPE = VIL, CEo and CE1 are double buffered when FT/PIPE = VIH, i.e. the signals take two cycles to deselect.

Industrial and Commercial Temperature Ranges

Industrial and Commercial Temperature Ranges

3750 tbl 05

Recommended Operating Temperature and Supply Voltage⁽¹⁾

Grade	Ambient Temperature	GND	VDD
Commercial	0°C to +70°C	0V	3.3V <u>+</u> 0.3V
Industrial	-40°C to +85°C	0V	3.3V <u>+</u> 0.3V

NOTES:

1. This is the parameter TA. This is the "instant on" case temperature.

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vdd	Supply Voltage	3.0	3.3	3.6	V
Vss	Ground	0	0	0	V
Vih	Input High Voltage	2.2		V_{DD} + 0.3 $V^{(1)}$	V
VIL	Input Low Voltage	-0.3(2)		0.8	V

NOTES:

3750 tbl 04

1. VTERM must not exceed VDD +0.3V.

2. VIL \geq -1.5V for pulse width less than 10ns.

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Commercial & Industrial	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
TBIAS	Temperature Under Bias	-55 to +125	°C
Tstg	Storage Temperature	-65 to +150	۰C
Tjn	Junction Temperature	+150	٥C
Ιουτ	DC Output Current	50	mA
			3750 tbl 06

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

- 2. VTERM must not exceed VDD +0.3V for more than 25% of the cycle time or 10ns maximum, and is limited to \leq 20mA for the period of VTERM \geq VDD + 0.3V.
- 3. Ambient Temperature Under Bias. Chip Deselected.

Capacitance (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions ⁽²⁾	Max.	Unit
Cℕ	Input Capacitance	ViN = 3dV	9	pF
Cout ⁽³⁾	Output Capacitance	Vout = 3dV	10	рF
				3750 tbl 07

NOTES:

1. These parameters are determined by device characterization, but are not production tested.

2. 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.

3. COUT also references CI/O.

Industrial and Commercial Temperature Ranges

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (VDD = 3.3V ± 0.3V)

			70V9089/79S		70V90		
Symbol	Parameter	Test Conditions	Min.	Max.	Min.	Max.	Unit
lu	Input Leakage Current ⁽¹⁾	VDD = 3.3V, VIN = 0V to VDD	_	10		5	μA
LO	Output Leakage Current	\overline{CE}_0 = VIH or CE1 = VIL, VOUT = 0V to VDD	_	10		5	μA
Vol	Output Low Voltage	IoL = +4mA	_	0.4		0.4	V
Vон	Output High Voltage	Iон = -4mA	2.4	_	2.4		V

NOTE:

1. At VDD \leq 2.0V input leakages are undefined.

3750 tbl 08

70V9089/79X7 70V9089/79X6 70V9089/79X9 Com'l Only Com'l Only Com'l & Ind Typ.⁽⁴⁾ Typ.⁽⁴⁾ Typ.⁽⁴⁾ **Test Condition** Symbol Parameter Version Max. Max. Max. Unit \overline{CE}_{L} and $\overline{CE}_{R} = V_{IL}$ COM'L lcc Dynamic Operating S 220 395 200 335 180 260 mΑ Current 220 350 200 290 180 225 Outputs Disabled Т (Both Ports Active) $f = f_{MAX}^{(1)}$ IND S 180 270 L 180 235 Standby Current \overline{CE}_{L} and $\overline{CE}_{R} = V_{H}$ COM'L S ISB1 70 145 60 115 50 75 mΑ (Both Ports - TTL 70 130 60 100 50 65 $f = fMAX^{(1)}$ 1 Level Inputs) IND S 50 85 50 75 L ISB2 Standby Current COM'L S mΑ CE"A" = VIL and 150 280 130 240 110 170 (One Port - TTL \overline{CE} "B" = VH⁽³⁾ 150 250 130 210 110 150 L Level Inputs) Active Port Outputs Disabled, f=fMAX⁽¹⁾ IND S 110 180 110 160 L Full Standby Current Both Ports CER and COM'L S ISB3 1.0 5 1.0 5 mΑ 1.0 5 CEL > VDD - 0.2V (Both Ports L 0.4 3 0.4 3 0.4 3 CMOS Level Inputs) $VIN \ge VDD - 0.2V \text{ or}$ S $V_{IN} \le 0.2V, f = 0^{(2)}$ IND 5 1.0 04 Т 3 Full Standby Current ISB4 \overline{CE} "A" < 0.2V and COM'L S 270 230 mΑ 140 120 100 160 CE"B" ≥ VDD - 0.2V⁽⁵⁾ (One Port -140 200 100 140 Т 240 120 CMOS Level Inputs) $V_{IN} \ge V_{DD} - 0.2V \text{ or}$ $V_{IN} \leq 0.2V$, Active Port IND S 100 170 Outputs Disabled, $f = f_{MAX}^{(1)}$ 100 150 L 3750 tbl 09a

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽⁶⁾ (VDD = $3.3V \pm 0.3V$)

NOTES:

1. At f = fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of GND to 3V.

2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.

3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".

4. \underline{V}_{DD} = 3.3V, TA = $\underline{25}^{\circ}C$ for Typ, and are not production tested. Icc cc(f=0) = 90mA (Typ).

5. $\overline{CE}x = VIL$ means $\overline{CE}0x = VIL$ and CE1x = VIH

 $\overline{CE}x = V_{H}$ means $\overline{CE}_{0x} = V_{H}$ or $CE_{1x} = V_{L}$

 $\overline{CEx} \le 0.2V \text{ means } \overline{CEx} \le 0.2V \text{ and } CE_{1X} \ge V_{DD} - 0.2V$ $\overline{CEx} \ge V_{DD} - 0.2V \text{ means } \overline{CE}_{0X} \ge V_{DD} - 0.2V \text{ or } CE_{1X} \le 0.2V$

"X" represents "L" for left port or "R" for right port.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽⁶⁾ ($VDD = 3.3V \pm 0.3V$)(Cont'd)

					70V9089 Com'l		70V9089 Com'l	9/79X15 Only	
Symbol	Parameter	Test Condition	Versi	on	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Unit
lcc	Dynamic Operating Current	CEL and CER = V⊫ Outputs Disabled	COM'L	S L	150 150	240 205	130 130	220 185	mA
	(Both Ports Active)	n Ports Active) f = f _{MAX} ⁽¹⁾	IND	S L					
ISB1	Standby Current (Both Ports - TTL	\overline{CE}_{L} and $\overline{CE}_{R} = V_{IH}$ f = fMAX ⁽¹⁾	COM'L	S L	40 40	65 50	30 30	55 35	mA
	Level Inputs)		IND	S L					
ISB2	(One Port - TTL $\overline{CE}^{"B"} = V_{H}^{(3)}$	COM'L	S L	100 100	160 140	90 90	150 130	mA	
	Level Inputs)	Active Port Outputs Disabled, f=fMAX ⁽¹⁾	IND	S L					
ISB3	Full Standby Current (Both Ports -	Both Ports $\overline{CE}R$ and $\overline{CE}L \ge V_{DD} - 0.2V$	COM'L	S L	1.0 0.4	5 3	1.0 0.4	5 3	mA
	CMOS Level Inputs)	VIN > VDD - 0.2V or	IND	S L					
ISB4	Full Standby Current (One Port -	CE"B" > VDD - 0.2V ⁽⁵⁾	COM'L	S L	90 90	150 130	80 80	140 120	mA
	VIN		IND	S L					

NOTES:

3750 tbl 09b

1. At f = fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of GND to 3V.

2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.

3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".

4. VDD = 3.3V, TA = 25°C for Typ, and are not production tested. Icc cc(f=0) = 90mA (Typ).

5. $\overline{CEx} = V_{IL}$ means $\overline{CE}_{0x} = V_{IL}$ and $CE_{1x} = V_{IH}$

 $\overline{CEx} = VIH$ means $\overline{CE}_{0x} = VIH$ or $CE_{1x} = VIL$

 $\begin{array}{l} \overline{\text{CEx}} \leq 0.2 \text{V} \text{ means } \overline{\text{CE}} \text{ox} \leq 0.2 \text{V} \text{ and } \text{CE} \text{ix} \geq \text{V} \text{D} \text{ - } 0.2 \text{V} \\ \overline{\text{CEx}} \geq \text{V} \text{D} \text{ - } 0.2 \text{V} \text{ means } \overline{\text{CE}} \text{ox} \geq \text{V} \text{D} \text{ - } 0.2 \text{V} \text{ or } \text{CE} \text{ix} \leq 0.2 \text{V} \\ \end{array}$

CEX \geq VDD - 0.2V means CE0X \geq VDD - 0.2V or CE1X \leq 0.2

"X" represents "L" for left port or "R" for right port.

Industrial and Commercial Temperature Ranges

AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1,2 and 3

3750 tbl 10

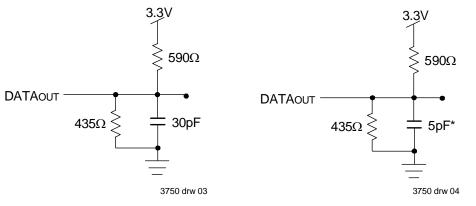
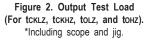


Figure 1. AC Output Test load.



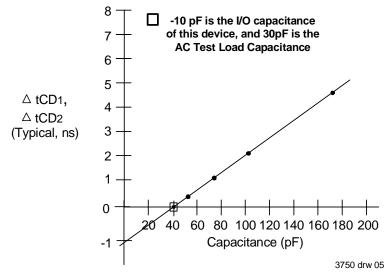


Figure 3. Typical Output Derating (Lumped Capacitive Load).

AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing)^(3,4) (VDD = $3.3V \pm 0.3$, TA = 0°C to +70°C)

		70V90 Com	89/79X6 I Only	70V90 Com	89/79X7 I Only	70V9089/79X9 Com'l & Ind		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) ⁽²⁾	19		22		25	—	ns
tCYC2	Clock Cycle Time (Pipelined) ⁽²⁾	10		12		15	—	ns
tCH1	Clock High Time (Flow-Through) ⁽²⁾	6.5	—	7.5		12	—	ns
tCL1	Clock Low Time (Flow-Through) ⁽²⁾	6.5		7.5		12	—	ns
tCH2	Clock High Time (Pipelined) ⁽²⁾	4	_	5	_	6	_	ns
tCL2	Clock Low Time (Pipelined) ⁽²⁾	4		5		6	—	ns
tR	Clock Rise Time	_	3		3		3	ns
tF	Clock Fall Time	_	3		3		3	ns
tsa	Address Setup Time	3.5		4		4	—	ns
tHA	Address Hold Time	0	-	0	_	1	—	ns
tsc	Chip Enable Setup Time	3.5		4		4	—	ns
tHC	Chip Enable Hold Time	0		0		1	—	ns
tsw	R/W Setup Time	3.5		4		4	—	ns
tHW	R/W Hold Time	0		0		1	—	ns
tsp	Input Data Setup Time	3.5		4		4	—	ns
tHD	Input Data Hold Time	0		0		1	—	ns
tsad	ADS Setup Time	3.5		4		4	—	ns
thad	ADS Hold Time	0		0		1		ns
tscn	CNTEN Setup Time	3.5		4		4	—	ns
tHCN	CNTEN Hold Time	0		0		1	—	ns
tsrst	CNTRST Setup Time	3.5		4		4	_	ns
tHRST	CNTRST Hold Time	0		0		1	_	ns
tOE	Output Enable to Data Valid		6.5		7.5		9	ns
toLZ	Output Enable to Output Low-Z ⁽¹⁾	2		2		2	_	ns
tонz	Output Enable to Output High-Z ⁽¹⁾	1	7	1	7	1	7	ns
tCD1	Clock to Data Valid (Flow-Through) ⁽²⁾		15		18		20	ns
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾	_	6.5		7.5		9	ns
toc	Data Output Hold After Clock High	2		2		2		ns
tскнz	Clock High to Output High-Z ⁽¹⁾	2	9	2	9	2	9	ns
tcĸız	Clock High to Output Low-Z ⁽¹⁾	2		2		2		ns
Port-to-Port	Delay	•	-	-	_	-	-	-
tcwdd	Write Port Clock High to Read Data Delay	_	24		28		35	ns
tccs	Clock-to-Clock Setup Time		9		10		15	ns

NOTES:

3750 tbl 11a

1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

2. The Pipelined output parameters (tcyc2, tcp2) apply to either or both left and right ports when FT/PIPE = VIH. Flow-through parameters (tcyc1, tcp1) apply when FT/PIPE = VIL for that port.

3. All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE) and FT/PIPE. FT/PIPE should be treated as a DC signal, i.e. steady state during operation.

AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing)^(3,4) (VDD = $3.3V \pm 0.3$, TA = 0°C to +70°C)(Cont'd)

		70V908 Com	9/79X12 I Only	70V90 Com	8979X15 'I Only	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
tCYC1	Clock Cycle Time (Flow-Through) ⁽²⁾	30		35		ns
tCYC2	Clock Cycle Time (Pipelined) ⁽²⁾	20		25		ns
tCH1	Clock High Time (Flow-Through) ⁽²⁾	12		12		ns
tCL1	Clock Low Time (Flow-Through) ⁽²⁾	12		12		ns
tCH2	Clock High Time (Pipelined) ⁽²⁾	8		10		ns
tCL2	Clock Low Time (Pipelined) ⁽²⁾	8		10		ns
tr.	Clock Rise Time		3		3	ns
tr	Clock Fall Time		3		3	ns
tsa	Address Setup Time	4		4		ns
tHA	Address Hold Time	1		1		ns
tsc	Chip Enable Setup Time	4		4		ns
tHC	Chip Enable Hold Time	1		1		ns
tsw	R/W Setup Time	4		4		ns
tHW	R/W Hold Time	1		1		ns
tsp	Input Data Setup Time	4		4		ns
tHD	Input Data Hold Time	1		1		ns
tsad	ADS Setup Time	4		4		ns
t had	ADS Hold Time	1		1		ns
tSCN	CNTEN Setup Time	4		4		ns
tHCN	CNTEN Hold Time	1		1		ns
tSRST	CNTRST Setup Time	4		4		ns
tHRST	CNTRST Hold Time	1		1		ns
tOE	Output Enable to Data Valid		12		15	ns
tolz	Output Enable to Output Low-Z ⁽¹⁾	2		2		ns
tонz	Output Enable to Output High-Z ⁽¹⁾	1	7	1	7	ns
tCD1	Clock to Data Valid (Flow-Through) ⁽²⁾		25		30	ns
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾		12		15	ns
tDC	Data Output Hold After Clock High	2		2		ns
tскнz	Clock High to Output High-Z ⁽¹⁾	2	9	2	9	ns
tCKLZ	Clock High to Output Low-Z ⁽¹⁾	2		2		ns
Port-to-Port	Delay					
tCWDD	Write Port Clock High to Read Data Delay		40		50	ns
tccs	Clock-to-Clock Setup Time	_	15		20	ns

3750 tbl 11b

NOTES:

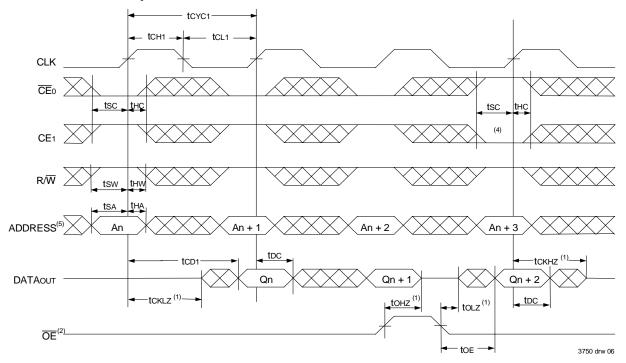
1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).

This parameter is guaranteed by device characterization, but is not production tested.

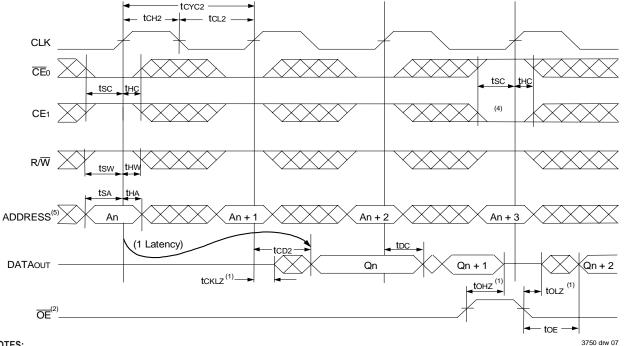
2. The Pipelined output parameters (tcyc2, tcD2) apply to either or both left and right ports when FT/PIPE = VIH. Flow-through parameters (tcyc1, tcD1) apply when FT/PIPE = VIL for that port.

3. All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE) and FT/PIPE. FT/PIPE should be treated as a DC signal, i.e. steady state during operation.

Timing Waveform of Read Cycle for Flow-Through Output $(\overline{FT}/PIPE^{*}x^{*} = VIL)^{(3,6)}$

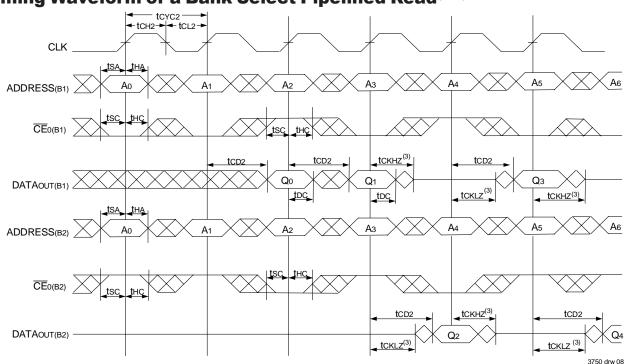


Timing Waveform of Read Cycle for Pipelined Output $(\overline{FT}/PIPE_{x} = VIH)^{(3,6)}$

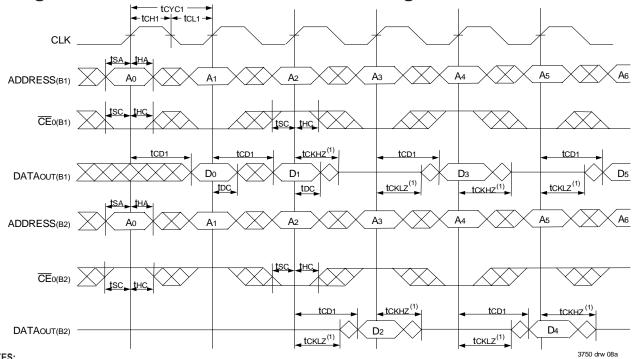


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. OE is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3. ADS = VIL, CNTEN and CNTRST = VIH.
- 4. The output is disabled (High-impedance state) by \overline{CE}_0 = VIH or CE1 = VIL following the next rising edge of clock. Refer to Truth Table 1.
- 5. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for
- reference use only. 6. "x" denotes Left or Right port. The diagram is with respect to that port.

Timing Waveform of a Bank Select Pipelined Read^(1,2)

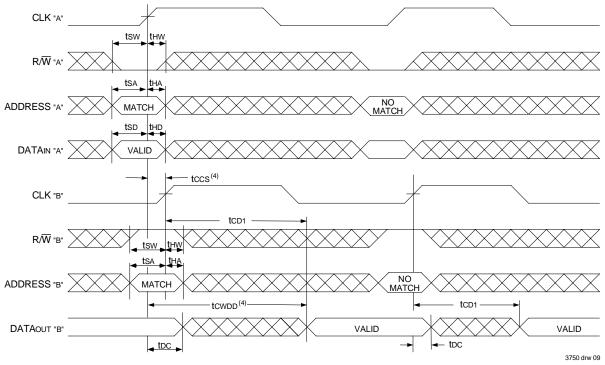


Timing Waveform of a Bank Select Flow-Through Read⁽⁶⁾



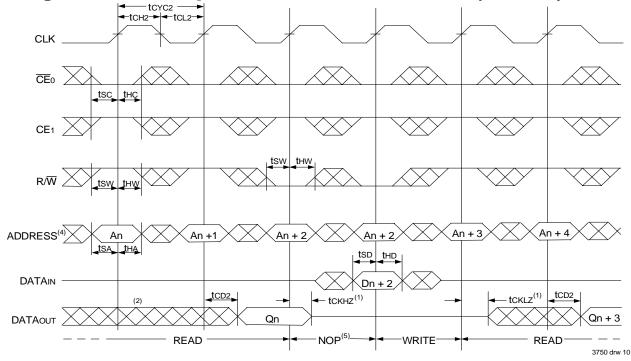
- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT70V9089/79 for this waveform,
- and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2. \overline{OE} and \overline{ADS} = VIL; CE1(B1), CE1(B2), R/W, \overline{CNTEN} , and \overline{CNTRST} = VIH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4. \overline{CE}_0 and \overline{ADS} = VIL; CE1, \overline{CNTEN} , and \overline{CNTRST} = VIH.
- 5. \overline{OE} = VIL for the Right Port, which is being read from. \overline{OE} = VIH for the Left Port, which is being written to.
- 6. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwdd.
- If tccs > maximum specified, then data from right port READ is not valid until tccs + tcD1. tcwDD does not apply in this case.

Timing Waveform Port-to-Port Flow-Through Read^(1,2,3,5)

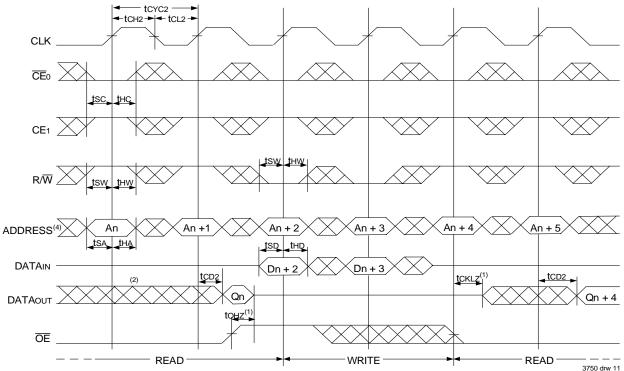


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. CE0 and ADS = VIL; CE1, CNTEN, and CNTRST = VIH.
- 3. $\overline{OE} = V_{IL}$ for the Port "B", which is being read from. $\overline{OE} = V_{IH}$ for the Port "A", which is being written to.
- 4. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwpp. If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwpp does not apply in this case.
- All timing is the same for both left and right ports. Port "A" may be either left or right port. Port "B" is the opposite of Port "A".



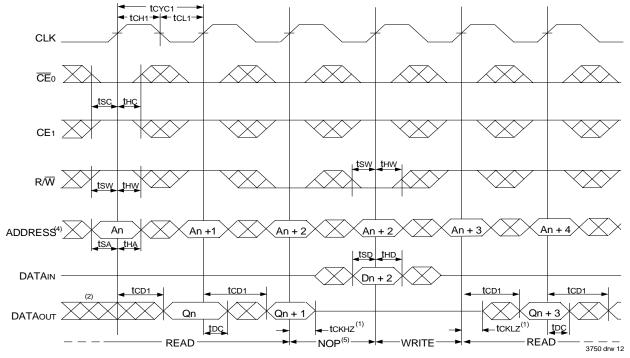


Timing Waveform of Pipelined Read-to-Write-to-Read (OE Controlled)⁽³⁾

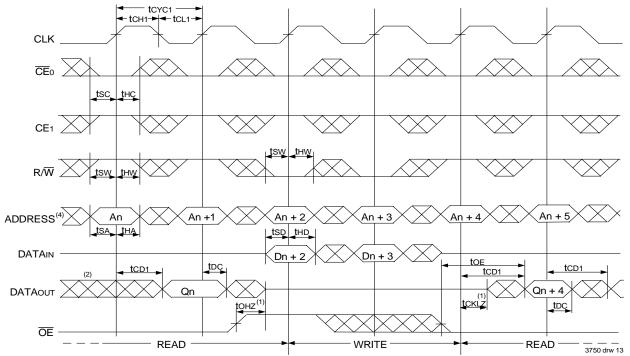


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. CEo and ADS = VIL; CE1, CNTEN, and CNTRST = VIH.
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.



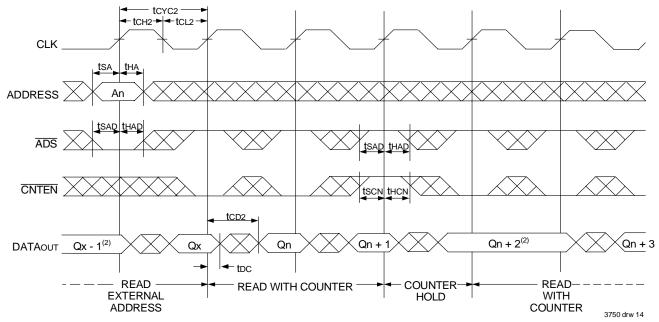


Timing Waveform of Flow-Through Read-to-Write-to-Read (\overline{OE} Controlled)⁽³⁾

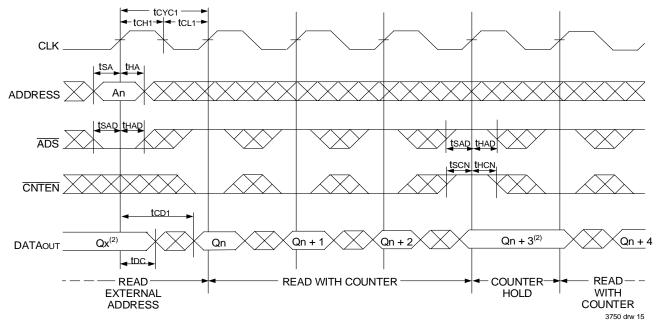


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. TEO and ADS = VIL; CE1, TOTEN, and TOTRST = VIH.
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

Timing Waveform of Pipelined Read with Address Counter Advance⁽¹⁾

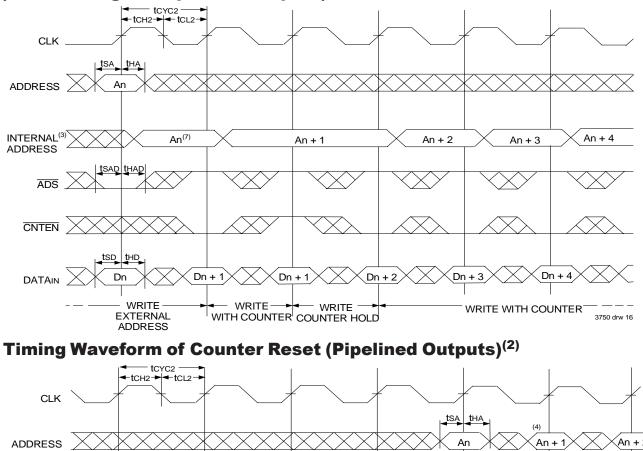


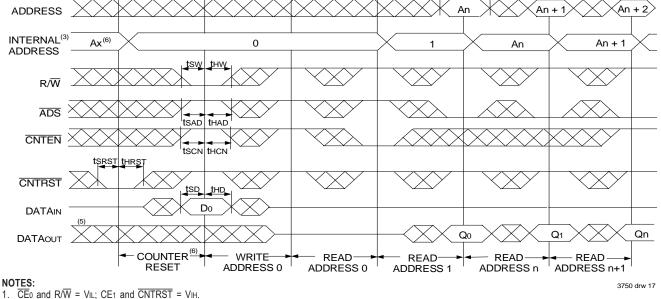




- 1. \overline{CE}_0 and \overline{OE} = VIL; CE1, R/W, and \overline{CNTRST} = VIH.
- 2. If there is no address change via ADS = VIL (loading a new address) or CNTEN = VIL (advancing the address), i.e. ADS = VIH and CNTEN = VIH, then the data output remains constant for subsequent clocks.

Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)⁽¹⁾





- 2. $\overline{CE}_0 = V_{IL}$; $CE_1 = V_{IH}$.
- 3. The "Internal Address" is equal to the "External Address" when ADS = VIL and equals the counter output when ADS = VIH.
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 6. No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset.ADDR0 will be accessed. Extra cycles are shown here simply for clarification.
- CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance. 7. The 'An +1' address is written to during this cycle.

Industrial and Commercial Temperature Ranges

Functional Description

The IDT70V9089/79 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

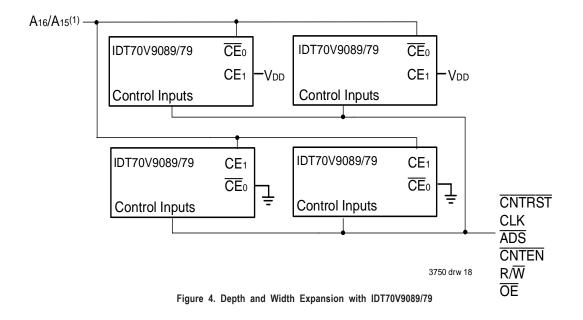
An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to stall the operation of the counter registers for fast interleaved memory applications.

A HIGH on \overline{CE}_0 or a LOW on CE1 for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70V9089/79's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with \overline{CE}_0 LOW and CE1 HIGH to re-activate the outputs.

Depth and Width Expansion

The IDT70V9089/79 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

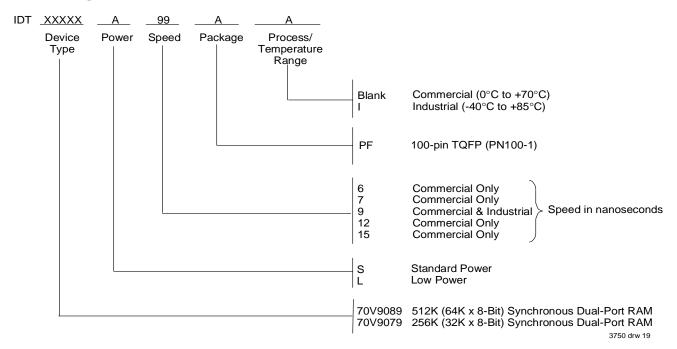
The IDT70V9089/79 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the varioius devices as required to allow for 16-bit or wider applications.



NOTE:

1. A16 is for ID70V9089. A15 is for ID70V9079.

Ordering Information



Ordering Information for Flow-through Devices

Old Flow-through Part	New Combined Part		
70V908S/L25	70V9089S/L12		
70V908S/L30	70V9089S/L15		

3750 tbl 12

Old Flow-through Part	New Combined Part				
70V908S/L25	70V9079S/L12				
70V908S/L30	70V9079S/L15				

3750 tbl 13

IDT Clock Solution for IDT70V9089/79 Dual-Port

	Dual-Port I/O Specitications		Clock Specifications			IDT	IDT	
IDT Dual-Port Part Number	Voltage	I/O	Input Capacitance	Input Duty Cycle Requirement	Maximum Frequency	Jitter Tolerance	IDT PLL Clock Device	Non-PLL Clock Device
70V9089/79	3.3	LVTTL	9pF	40%	100	150ps	2305 2308 2309	49FCT3805 49FCT3805D/E 74FCT3807 74FCT3807D/E

3750 tbl 14

Datasheet Document History

1/18/99:	Initiated datasheet document history							
	Converted to new format							
	Cosmetic and typographical corrections							
	Added additional notes to pin configurations							
	Page 14 Added Depth and Width Expansion section.							
6/11/99:	Page 3 Deleted note 6 for Table II							
11/12/99:	Replaced IDT logo							
3/31/00:	Combined Pipelined 70V9089 family and Flow-through 70V908 family offerings into one data sheet							
	Changed ±200mV in waveform notes to 0mV							
	Added corresponding part chart with ordering information							
1/10/01:	Page 3 Changed information in Truth Table II							
	Page 4 Increased storage temperature parameters							
	Clarified TA parameter							
	Page 5 DC Electrical parameters-changed wording from "open" to "disabled"							
	Removed Preliminary Status							
01/15/04:	Consolidated multiple devices into one datasheet							
	Changed naming conventions from Vcc to Vbb and from GND to Vss							
	Removed I-temp footnote from tables							
	Page 2 Added date revision to pin configuration							
	Page 4 Added JunctionTemperature to Absolute Maximum Ratings Table							
	Added Ambient Temperature footnote							
	Page 5 Added I-temp numbers for 9ns speed to the DC Electrical Characteristics Table							
	Added 6ns & 7ns speeds DC power numbers to the DC Electrical Characteristics Table							
	Page 7 Added I-temp for 9ns speed to AC Electrical Characteristics Table							
	Added 6ns & 7ns speeds AC timing numbers to the AC Electrical Characteristics Table							
	Page 16 Added 6ns & 7ns speeds grade and 9ns I-temp to ordering information							
	Added IDT Clock Solution Table							
	Page 1 & 17 Replaced ® IDT logo with ™ new logo							
05/11/04:	Page 1 & 19 Added 7ns speed grade to ordering information							
	Page 5 Added 7ns speed DC power numbers to the DC Electrical Characteristics Table							
	Page 8 Added 7ns speed AC timing numbers to the AC Electrical Characteristics Table							



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